

Device Material Content

5555 NE Moore Ct.							Assembly	: ASEK	
Hillsboro OR 97124					Package Code:		Size (mm)		
custreq@latticesemi.com	Package: Total Device Weight		256 F	OWLP	ASG256		Lead pitch (mm): 0.5		
				Milligrams	Products:	MSL: 3 Reflow max (°C): 260			
April, 2025			212112		LFCPNX-100				
Арги, 2023	% of Total		% of Total				, ,		
	Pkg. Wt.	Weight (mg)	Pkg. Wt.	Weight (mg)	Substance	CAS#	% of Subst.	Notes / Assumptions:	
Die	50.642%	75.702	50.64%	75.702	Silicon chip	7440-21-3	100.00%		
M III G	24.07.007	27.224							
Mold Compound	24.968%	37.324	2.257%	3.374	Proprietary Epoxy/Phenol Resins		9.04%	SUMIKON® EME-QXG01	
			18.811%	28.119	Silica(Amorphous) A	60676-86-0	75.34%	SOMIKON® EME-QAGOT	
				5.624	Silica(Amorphous) A Silica(Amorphous) B	7631-86-9	15.07%		
			3.762%						
			0.138%	0.206	Carbon Black	1333-86-4	0.55%		
Polyimide 1	0.449%	0.670						Repassivation Polyimide LTC9320-E07	
·			0.449%	0.670	Polyimide Resin	-	100.00%		
RDL 1	1.171%	1.751							
			1.157%	1.730	Copper (Cu)	7440-50-8	98.82%		
			0.014%	0.021	Titanium (Ti)	7440-32-6	1.18%		
RDL 2	2.663%	3.980							
KDL 2	2.00370	3.760	2.649%	3.960	Copper (Cu)	7440-50-8	99.48%		
							0.52%		
			0.014%	0.021	Titanium (Ti)	7440-32-6	0.52%		
Polyimide 2	0.889%	1.329						Repassivation Polyimide LTC9320-E07	
			0.889%	1.329	Polyimide Resin	-	100.00%		
Polyimide 3	0.889%	1.329						Repassivation Polyimide LTC9320-E07	
1 orymnuc 3	0.00570	1.52)	0.889%	1.329	Polyimide Resin	_	100.00%	Repussivation Folyminde ET C/320 E07	

UBM	0.114%	0.171	0.01.40/	0.021	Ti' (Ti'.)	7440.33.5	12.1.40/		
			0.014%	0.021	Titanium (Ti)	7440-32-6	12.14%		
			0.100%	0.150	Copper (Cu)	7440-50-8	87.86%		
Bump	18.216%	27.230							
			16.394%	24.507	Tin	7440-31-5	90.00%	SACQ	
	l I		0.729%	1.089	Silver	7440-22-4	4.00%		
			0.146%	0.218	Copper	7440-50-8	0.80%		
	l I		0.018%	0.027	Nickel	7440-02-0	0.10%		
	l I		0.929%	1.389	Bismuth	7440-69-9	5.10%		
			0.72770	1.507	Germanium	7440 07 7	3.1070		
	100.000%	149.486	100.000%	149.486					

Notes

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Rev. B